

Title (en)

DEVICE FOR MANUFACTURING THIN-PLATE LAMINATE HAVING FILM-SHAPED RESIN LAYER

Title (de)

VORRICHTUNG ZUR HERSTELLUNG EINES DÜNNPLATTENLAMINATS MIT FILMFÖRMIGER HARZSCHICHT

Title (fr)

DISPOSITIF DE FABRICATION D'UN STRATIFIÉ À PLAQUE MINCE AYANT UNE COUCHE DE RÉSINE EN FORME DE FILM

Publication

EP 3950272 A4 20221228 (EN)

Application

EP 20777450 A 20200318

Priority

- JP 2019056971 A 20190325
- JP 2020044239 A 20200313
- JP 2020011962 W 20200318

Abstract (en)

[origin: EP3950272A1] [Summary][Object] To provide a device for the production of a thin plate-like laminate having a film-like resin layer in which a concave/convex shape can stably be formed with high accuracy on the film-like resin layer laminated on a thin plate-like substrate.[Achieving Means] There are provided a setting device 31 for creating a mold retention structure 100 in which molds 110 are arranged on both surface sides of a workpiece 85, a heating device 41 which heats the molds to a thermal deformation temperature of a film-like resin composition 84, a compression roller device 51 in which the mold retention structure, after heating of the molds, is introduced between two compression rollers 52, 54 and outer surfaces of the molds are compressed by rotating the compression rollers to integrally thermocompression-bond the film-like resin composition and a substrate 81 to form a thin plate-like laminate 80 having a film-like resin layer 82, and an extraction device 61 which extracts the molds from the mold retention structure after compression.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

- [Y] JP H10282315 A 19981023 - MATSUSHITA ELECTRIC IND CO LTD
- [Y] JP 2009158731 A 20090716 - HITACHI IND EQUIPMENT SYS & US 2009166914 A1 20090702 - OGINO MASAHIKO [JP], et al
- See also references of WO 2020196151A1

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